

# SN74AS230A OCTAL BUFFER/DRIVER WITH 3-STATE OUTPUTS

SDAS213B – DECEMBER 1982 – REVISED DECEMBER 1994

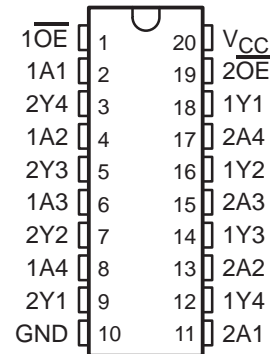
- True and Complementary Outputs
- 3-State Outputs Drive Bus Lines or Buffer Memory Address Registers
- High Capacitive-Drive Capability
- Current-Sinking Capability Up to 64 mA
- Package Options Include Plastic Small-Outline (DW) Packages and Standard Plastic (N) 300-mil DIPs

## description

This octal buffer/driver is designed specifically to improve the performance of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters. When used together, multiples of this device provide the choice of selected combinations of inverting and noninverting outputs, symmetrical active-low output-enable ( $\overline{OE}$ ) inputs, and complementary OE and  $\overline{OE}$  inputs.

The SN74AS230A is characterized for operation from 0°C to 70°C.

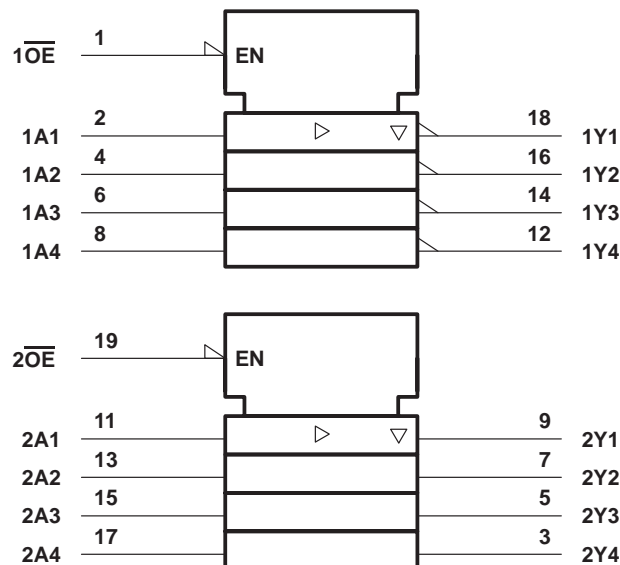
DW OR N PACKAGE  
(TOP VIEW)



FUNCTION TABLE  
(each buffer)

INPUTS		OUTPUT
$\overline{OE}$	A	Y
L	H	L
L	L	H
H	X	Z

## logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

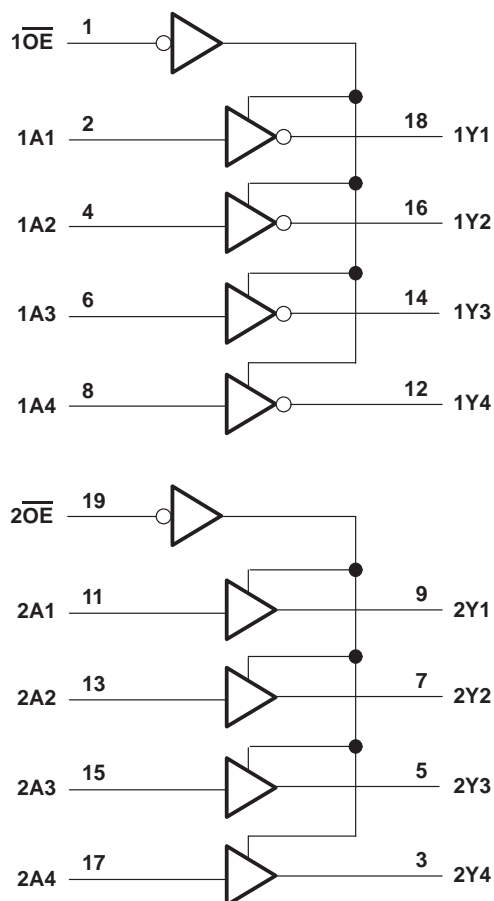
# SN74AS230A

## OCTAL BUFFER/DRIVER

### WITH 3-STATE OUTPUTS

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#### logic diagram (positive logic)



#### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)<sup>†</sup>

Supply voltage, $V_{CC}$	7 V
Input voltage, $V_I$	7 V
Voltage applied to a disabled 3-state output	5.5 V
Operating free-air temperature range, $T_A$	0°C to 70°C
Storage temperature range	–65°C to 150°C

<sup>†</sup> Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

#### recommended operating conditions

	MIN	NOM	MAX	UNIT
$V_{CC}$ Supply voltage	4.5	5	5.5	V
$V_{IH}$ High-level input voltage	2			V
$V_{IL}$ Low-level input voltage			0.8	V
$I_{OH}$ High-level output current			–15	mA
$I_{OL}$ Low-level output current			64	mA
$T_A$ Operating free-air temperature	0		70	°C



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**electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)**

PARAMETER		TEST CONDITIONS		MIN	TYP†	MAX	UNIT	
V <sub>IK</sub>		V <sub>CC</sub> = 4.5 V, I <sub>I</sub> = −18 mA				−1.2	V	
V <sub>OH</sub>		V <sub>CC</sub> = 4.5 V to 5.5 V, I <sub>OH</sub> = −2 mA		V <sub>CC</sub> − 2		V		
		V <sub>CC</sub> = 4.5 V		I <sub>OH</sub> = −3 mA			2.4	3.4
				I <sub>OH</sub> = −15 mA			2.4	
V <sub>OL</sub>		V <sub>CC</sub> = 4.5 V, I <sub>OL</sub> = 64 mA		0.31		0.55	V	
I <sub>OZH</sub>		V <sub>CC</sub> = 5.5 V, V <sub>O</sub> = 2.7 V				50	μA	
I <sub>OZL</sub>		V <sub>CC</sub> = 5.5 V, V <sub>O</sub> = 0.4 V				−50	μA	
I <sub>I</sub>		V <sub>CC</sub> = 5.5 V, V <sub>I</sub> = 7 V				0.1	mA	
I <sub>IH</sub>		V <sub>CC</sub> = 5.5 V, V <sub>I</sub> = 2.7 V				20	μA	
I <sub>IL</sub>	2A inputs	V <sub>CC</sub> = 5.5 V, V <sub>I</sub> = 0.4 V				−1	mA	
	All other inputs					−0.5		
I <sub>O‡</sub>		V <sub>CC</sub> = 5.5 V, V <sub>O</sub> = 2.25 V		−50		−150	mA	
I <sub>CC</sub>		V <sub>CC</sub> = 5.5 V		Outputs high		16	25	mA
				Outputs low		55	87	
				Outputs disabled		29	46	

† All typical values are at  $V_{CC} = 5\text{ V}$ ,  $T_A = 25^\circ\text{C}$ .

‡ The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current,  $I_{OS}$ .

### switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 4.5\text{ V to }5.5\text{ V}$ , $C_L = 50\text{ pF}$ , $R_1 = 500\ \Omega$ , $R_2 = 500\ \Omega$ , $T_A = \text{MIN to MAX}\S$		UNIT
			MIN	MAX	
$t_{PLH}$	1A	1Y	2	6.5	ns
$t_{PHL}$			1	5.7	
$t_{PLH}$	2A	2Y	2	6.2	ns
$t_{PHL}$			1	6.2	
$t_{PZH}$	$1\overline{OE}$	1Y	2	6.4	ns
$t_{PZL}$			2	8.5	
$t_{PHZ}$	$1\overline{OE}$	1Y	2	6	ns
$t_{PLZ}$			2	9.5	
$t_{PZH}$	$2\overline{OE}$	2Y	2	9	ns
$t_{PZL}$			2	7.5	
$t_{PHZ}$	$2\overline{OE}$	2Y	2	6	ns
$t_{PLZ}$			2	9	

§ For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

# SN74AS230A

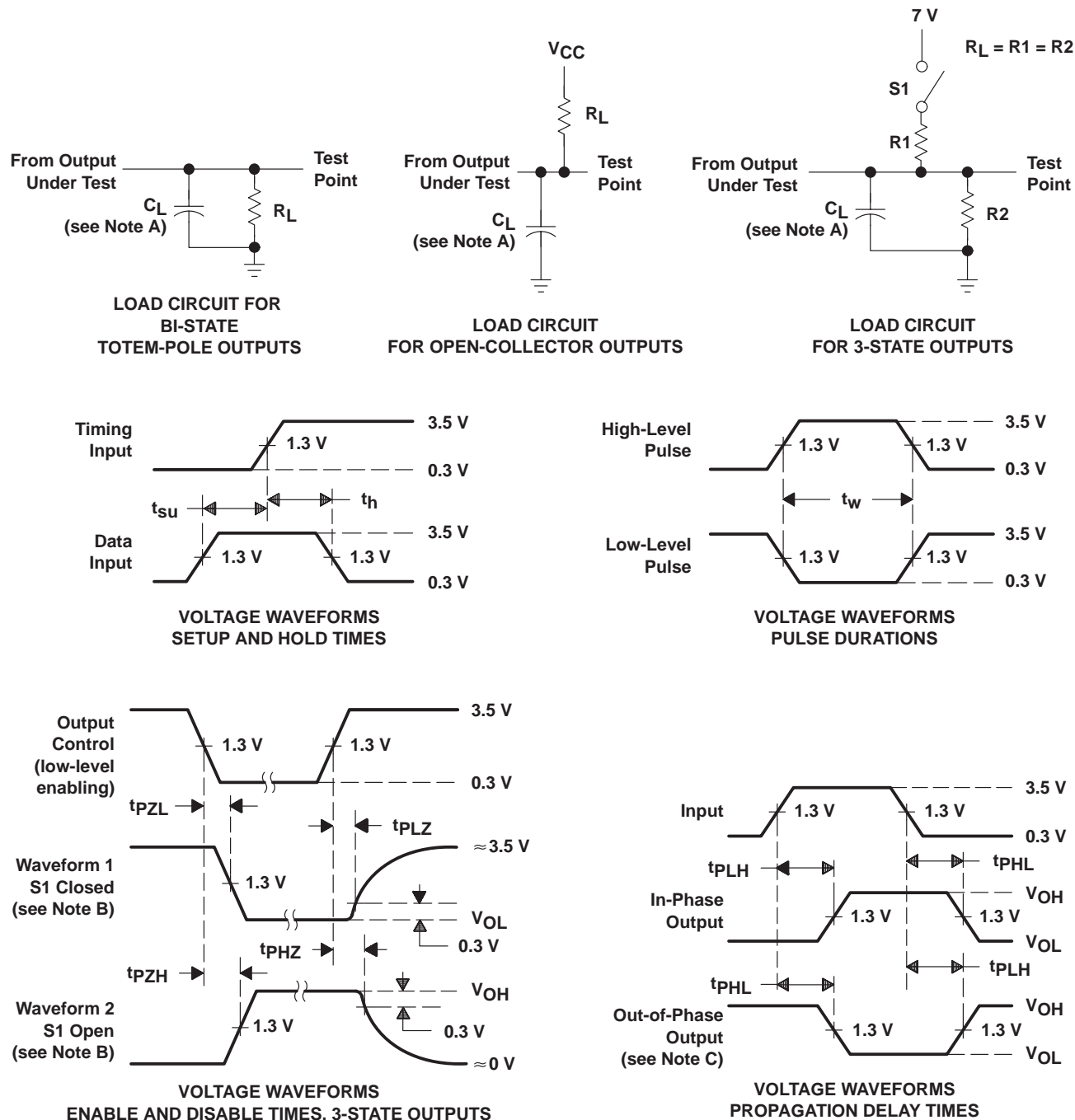
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#### PARAMETER MEASUREMENT INFORMATION

#### SERIES 54ALS/74ALS AND 54AS/74AS DEVICES



- NOTES:
- A.  $C_L$  includes probe and jig capacitance.
  - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
  - C. When measuring propagation delay items of 3-state outputs, switch S1 is open.
  - D. All input pulses have the following characteristics:  $PRR \leq 1$  MHz,  $t_r = t_f = 2$  ns, duty cycle = 50%.
  - E. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms

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